

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE5011	**Issued**	28. August 2013
MA#	MA000983744		
Package	PG-DSO-8-16	**Weight***	83.39 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.837	3.40	3.40	34015	34015
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8600	
	non noble metal	copper	7440-50-8	29.121	34.92	35.83	349212	358350
wire	noble metal	gold	7440-57-5	0.151	0.18	0.18	1810	1810
encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1143	
	plastics	epoxy resin	-	4.386	5.26		52597	
	inorganic material	silicondioxide	60676-86-0	43.193	51.81	57.18	517964	571704
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9759	9759
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7798	7798
glue	plastics	acrylic resin	-	0.304	0.36		3644	
	noble metal	silver	7440-22-4	1.077	1.29	1.65	12920	16564
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com